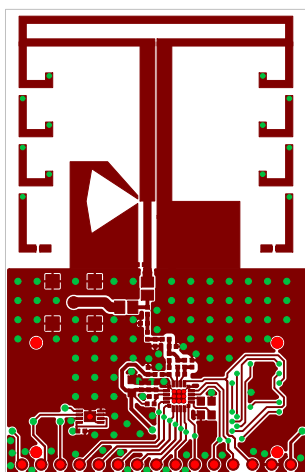
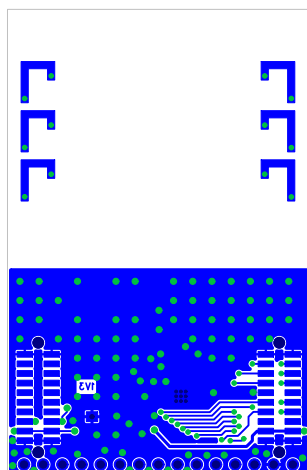


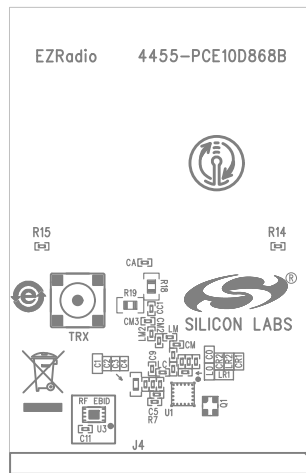
TOP WIRE

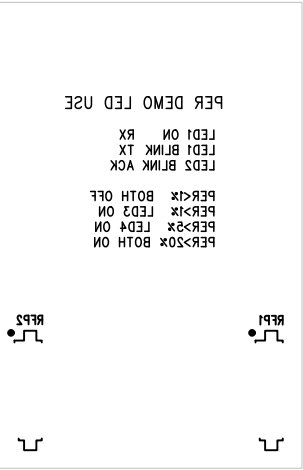




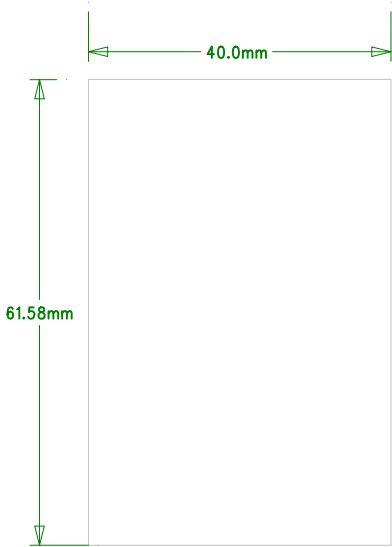
BOTTOM WIRE

TOP ASSEMBLY
TOP SILKSCREEN

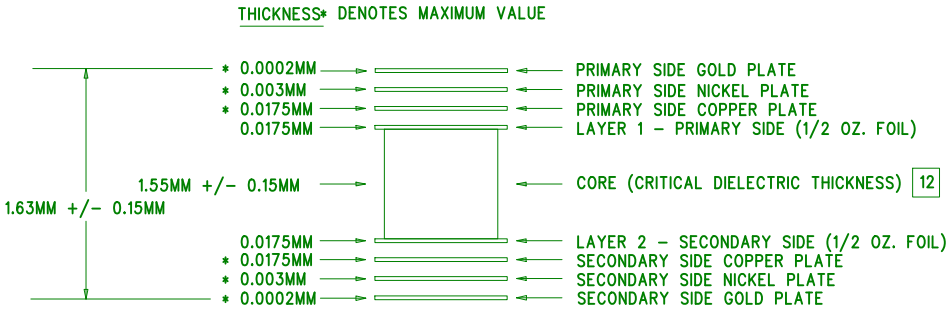




BOTTOM SILKSCREEN



- MANUFACTURING NOTES: (UNLESS OTHERWISE SPECIFIED)
- 1. MATERIAL: COPPER CLAD EPOXY GLASS FR-4 BASE MATERIAL.
COPPER CLADDING SHALL BE TYPE "HTE" WITH A WEIGHT OF 1/2 OZ/SQ FT. FOR EXTERNAL LAYERS AND 1/2 OZ/SQ FT. FOR INTERNAL LAYERS AND/OR PLANES.
MINIMUM WEIGHT AFTER PLATING OF EXTERNAL LAYERS SHALL BE 1 OZ/SQ FT.
 - 2. TOTAL BOARD THICKNESS SHALL BE 1.63 +/-0.15 mm. LAYER SEQUENCING SHALL BE CONSECUTIVE AS ESTABLISHED BY THE MASTER PATTERN LAYER SCHEDULE SHOWN.
 - 3. LAYER TO LAYER REGISTRATION OF THE CONDUCTOR PATTERNS SHALL BE WITHIN 0.10 mm DIA. TRUE POSITION, WITH AN ABSOLUTE MINIMUM OF 0.05 mm BETWEEN PLATED-THRU HOLE WALLS AND ADJACENT CONDUCTIVE SURFACES. END PRODUCT LINE WIDTH AND TERMINAL AREAS SHALL NOT DEVIATE FROM THE 1:1 MASTER PATTERN IMAGE BY MORE THAN +0.025 mm, -0.075 mm FOR 1/2 OZ. COPPER.
 - 4. ALL PLATED-THROUGH HOLES TO HAVE A MINIMUM COPPER WALL THICKNESS OF 0.025 mm. PLATING SHALL BE CONTINUOUS. DO NOT FILL VIAS
 - 5. HOLE SIZE TOLERANCES SHALL BE:
PLATED-THROUGH HOLES > 0.50 mm SHALL BE +/- 0.075 mm.
UNPLATED THROUGH HOLES SHALL BE +/- 0.05 mm.
TOLERANCES APPLY AFTER PLATING.
 - 6. FINISH: GOLDPLATED ON FOOTPRINTS AND PADS 0.0002 mm MAX.
 - 7. SOLDERMASK: SOLDERMASK OVER BARE COPPER - COLOR : BLUE
 - 8. SILKSCREEN: SILKSCREEN TOP SIDE ONLY USING NON-CONDUCTIVE WHITE EPOXY INK.
 - 9. THE PCB WARP AND TWIST SHALL NOT EXCEED 1 %
 - 10. HOLE TO EDGE TOLERANCE SHALL NOT VARY MORE THAN +/- 0.25 mm.
 - 11. ALL TOLERANCES ARE NON-ACCUMULATIVE.
 - 12. ALL 1.27 mm TRACES ON LAYER 1 OR LAYER 2 ARE 50 OHM +/- 5 OHM IMPEDANCE CONTROLLED TRACES. IMPEDENCE CALCULATIONS ARE MADE ASSUMING A DIELECTRIC CONSTANT OF 4.6 FOR CRITICAL PRE-PREG LAYER. IF DIELECTRIC CONSTANT IS NOT 4.6 VENDOR SHALL ADJUST TRACE WIDTH TO ACHIEVE 50 OHMS.



LAYER SCHEDULE
SCALE: NONE 2